

General Description

The HSP8119 is the high cell density trench P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The HSP8119 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

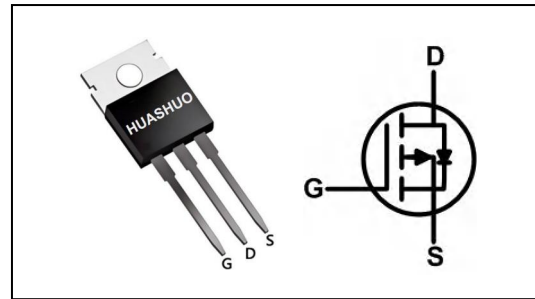
Features

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench Technology

Product Summary

V_{DS}	-80	V
$R_{DS(ON),typ}$	13.5	mΩ
I_D	-90	A

TO-220 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-80	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current, $-V_{GS}$ @ $-10V^1$	-90	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current, $-V_{GS}$ @ $-10V^1$	-60	A
I_{DM}	Pulsed Drain Current ²	-270	A
EAS	Single Pulse Avalanche Energy ³	710	mJ
I_{AS}	Avalanche Current	63	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation ⁴	210	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	0.73	$^\circ\text{C/W}$



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-80	---	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-10V, I _D =-20A	---	13.5	15	mΩ
		V _{GS} =-4.5V, I _D =-10A	---	14.5	17	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.0	-1.8	-2.5	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-80V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =-80V, V _{GS} =0V, T _J =55°C	---	---	10	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
R _g	Gate Resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz	---	1.7	---	Ω
g _{fs}	Forward Transconductance	V _{DS} =-10V, I _D =-3A	---	30	---	S
Q _g	Total Gate Charge	V _{DS} =-40V, V _{GS} =-10V, I _D =-10A	---	190	---	nC
Q _{gs}	Gate-Source Charge		---	29	---	
Q _{gd}	Gate-Drain Charge		---	55	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-40V, V _{GS} =-10V, R _G =6Ω, I _D =-10A	---	25	---	ns
T _r	Rise Time		---	20	---	
T _{d(off)}	Turn-Off Delay Time		---	180	---	
T _f	Fall Time		---	88	---	
C _{iss}	Input Capacitance	V _{DS} =-40V, V _{GS} =0V, f=1MHz	---	13300	---	pF
C _{oss}	Output Capacitance		---	390	---	
C _{rss}	Reverse Transfer Capacitance		---	50	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,5}	V _G =V _D =0V, Force Current	---	---	-90	A
I _{SM}	Pulsed Source Current ^{2,5}		---	---	-270	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =-1A, T _J =25°C	---	---	-1.2	V
T _{rr}	Reverse Recovery Time	I _F =-20A, di/dt=100A/μs	---	35	---	ns
Q _{rr}	Reverse Recovery Charge	I _F =-20A, di/dt=100A/μs	---	45	---	nC

Note :

1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%

3.The EAS data shows Max. rating . The test condition is V_{DD}=-50V,V_{GS}=-10V,L=0.1mH,R_G=25Ω,I_{AS}=-63A

4.The power dissipation is limited by 150°C junction temperature

5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

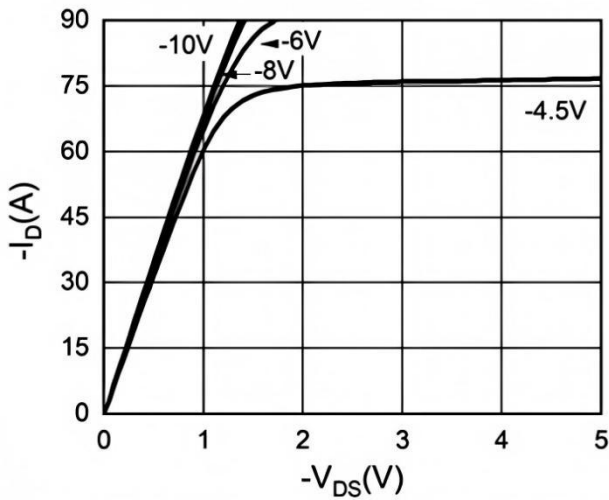


Fig.1 Typical Output Characteristics

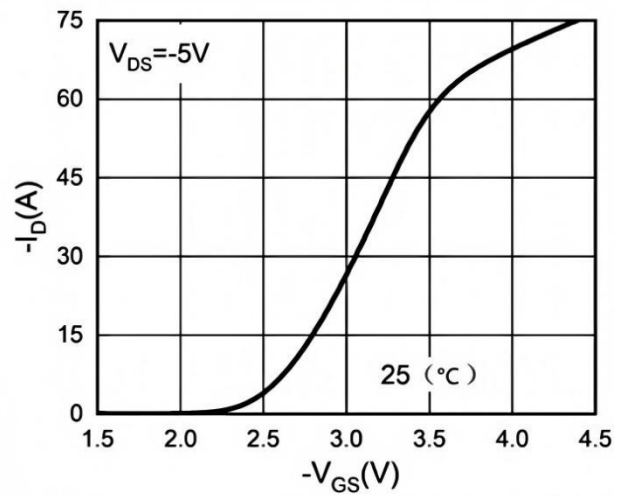


Fig.2 Transfer Characteristics

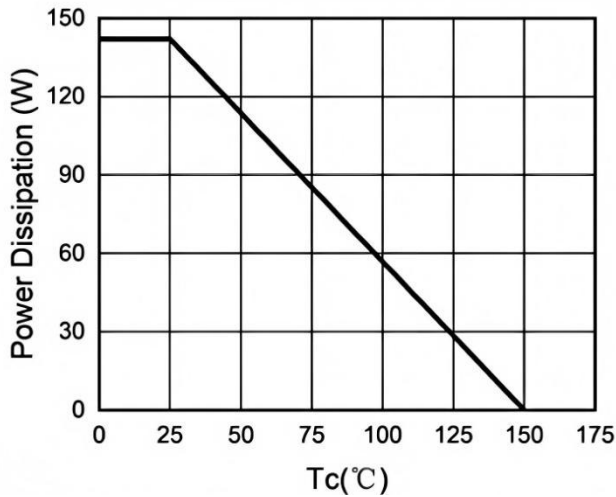


Fig.3 Power Dissipation

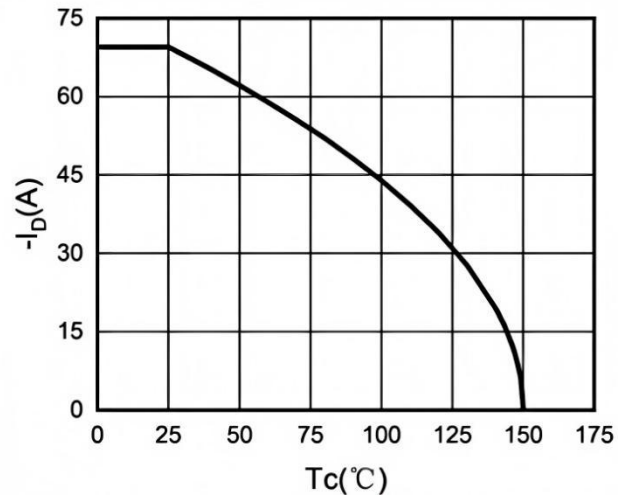


Fig.4 Drain Current

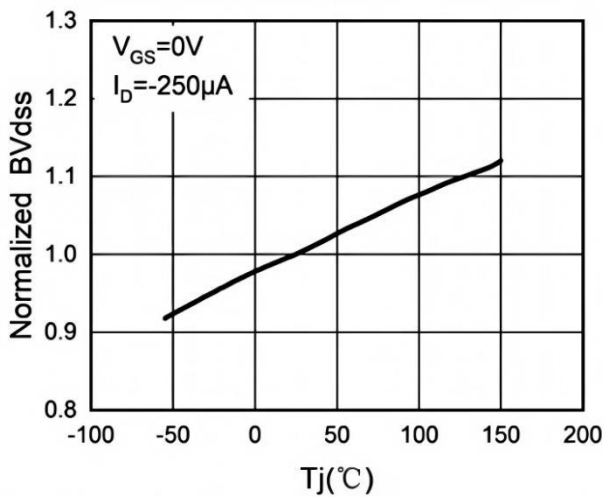


Fig.5 BV_{DS} vs Junction Temperature

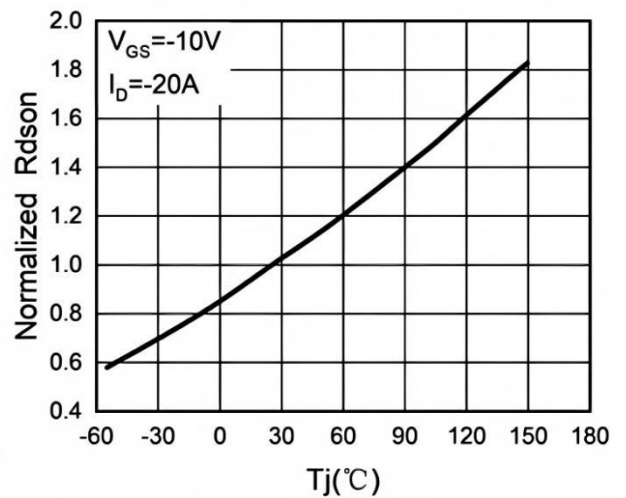


Fig.6 $R_{DS(on)}$ vs Junction Temperature



P-Ch 80V Fast Switching MOSFETs

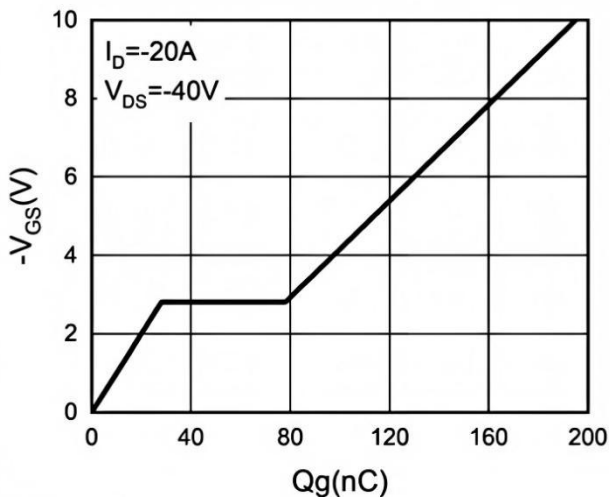


Fig.7 Gate Charge Waveforms

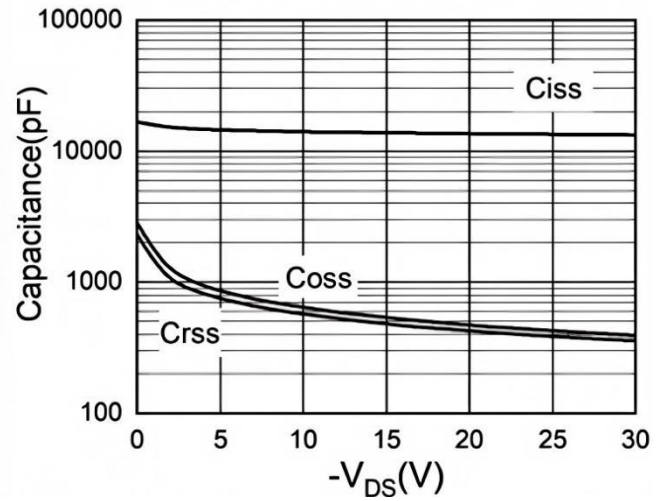


Fig.8 Capacitance

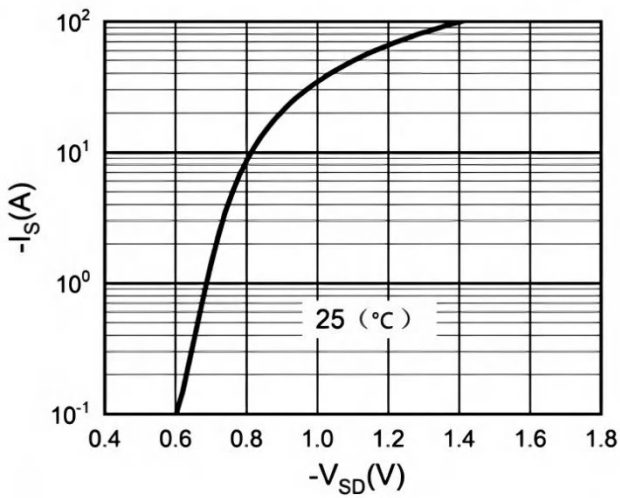


Fig.9 Body Diode Characteristics

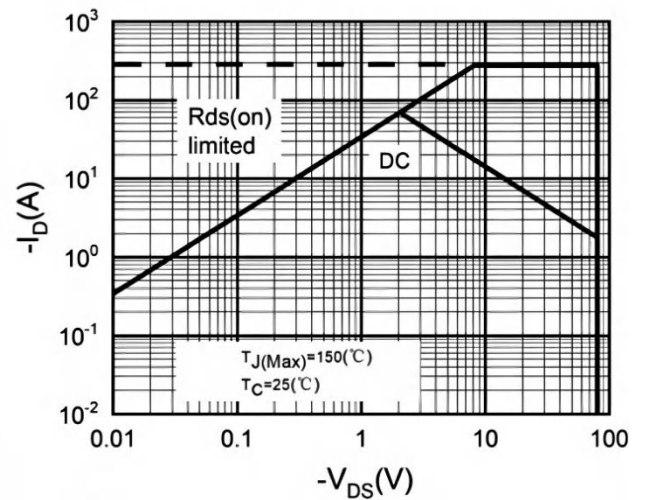


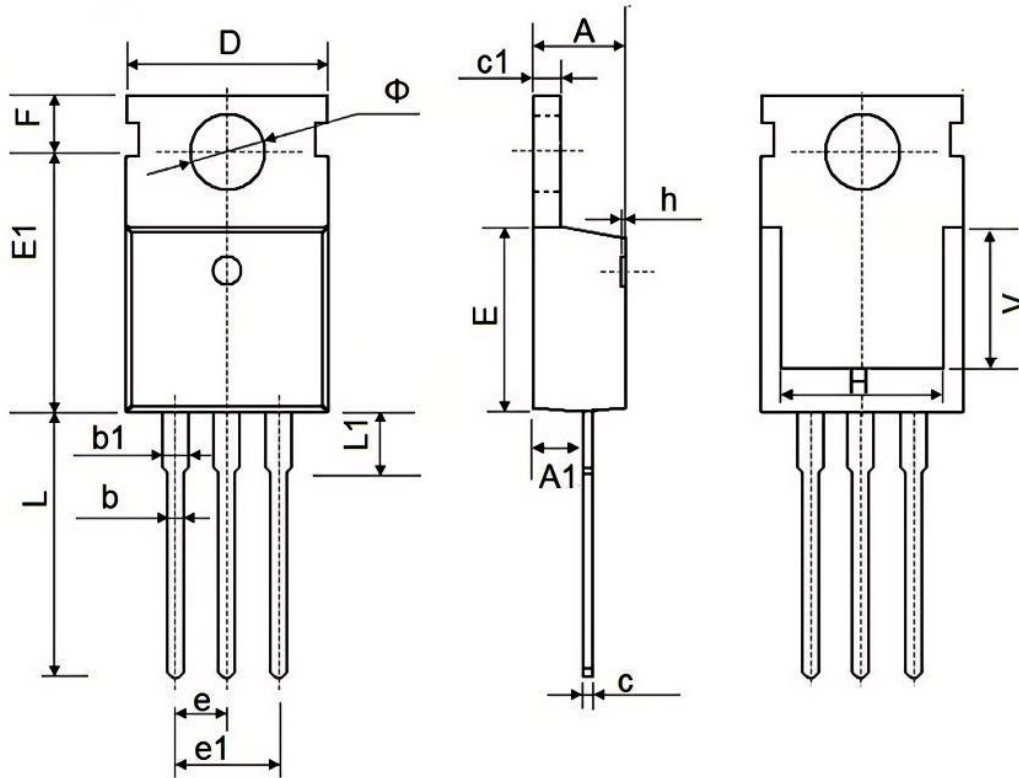
Fig.10 Maximum Safe Operating Area



Ordering Information

Part Number	Package code	Packaging
HSP8119	TO-220	1000/Box

TO-220 Package Outline



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.300	4.700	0.169	0.185
A1	2.200	2.600	0.087	0.102
b	0.700	0.950	0.028	0.037
b1	1.170	1.410	0.046	0.056
C	0.450	0.650	0.018	0.026
c1	1.200	1.400	0.047	0.055
D	9.600	10.400	0.378	0.409
E	8.8500	9.750	0.348	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.750	14.300	0.502	0.563
L1	2.850	3.950	0.112	0.156
V	7.500 REF.		0.295 REF.	
Φ	3.400	4.000	0.134	0.157



HSP8119 Marking:

